

Final Product Change Notification

Issue Date:27-Jan-2017Effective Date:27-Apr-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

201612008F01



QUALITY

Change Category

[] Wafer Fab Process

[] Wafer Fab Materials

[] Wafer Fab Location

iMX6ULL Molding Compound Change From G770FL to G770SFL

[] Assembly [] Product Marking []Test [] Design Process Location [X] Assembly[] Mechanical []Test [] Errata Materials Specification Process [] Assembly [] []Test [] Electrical Location Packing/Shipping/Labeling Equipment spec./Test coverage

Details of this Change

NXP Semiconductors is announcing the successful qualification of molding compound change from G770FL to G770SFL (low alpha) for i.MX6ULL 14x14 BGA and 9x9 BGA parts. G770SFL(low alpha) had better performance than G770FL on SER failure rate.

Why do we Implement this Change

Molding compound change from G770FL to G770SFL(low alpha) will improve SER performance. Molding compound G770FL and G770SFL(low alpha) have same composition. G770SFL(low alpha) molding compound has better control on alpha particle than G770FL. Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 01-Mar-2017 The available sample part number is PCIMX6Y2DVM05AA. Production

Planned first shipment 30-Apr-2017

Impact

There is no change to product form, fit, function, or reliability.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 26-Feb-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Carl Li

Position Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Customer Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
MCIMX6Y0CVM05AA	MCIMX6Y0CVM05AA	935332946699	MCIMX6Y0CVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y1CVM05AA	MCIMX6Y1CVM05AA	935320915699	MCIMX6Y1CVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y2DVM05AA	MCIMX6Y2DVM05AA	935313074699	MCIMX6Y2DVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y0CVM05AA	MCIMX6Y0CVM05AA	935332946699	MCIMX6Y0CVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y1CVM05AA	MCIMX6Y1CVM05AA	935320915699	MCIMX6Y1CVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y2DVM05AA	MCIMX6Y2DVM05AA	935313074699	MCIMX6Y2DVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers